



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN#20160726001
New Carrier Tape
Information Only**

Date: 7/27/2016
To: PREMIER FARNELL PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this PCN are for your information only. Please see the attachment details for the planned implementation date.

This notification period is per TI's standard process. Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20160726001
Attachment: 1
Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74AVC1T45DCKR	null
SN74LVC1G11MDCKREP	null
SN74LVC2G04MDCKREP	null
TS5A9411DCKT	null
SN74AVCH1T45DCKR	null
SN74LVC1T45MDCKREP	null
SN74LVC2G17MDCKREP	null
TPS3803-01MDCKREP	null
TS5A9411DCKR	null

Technical details of this Product Change follow on the next page(s).

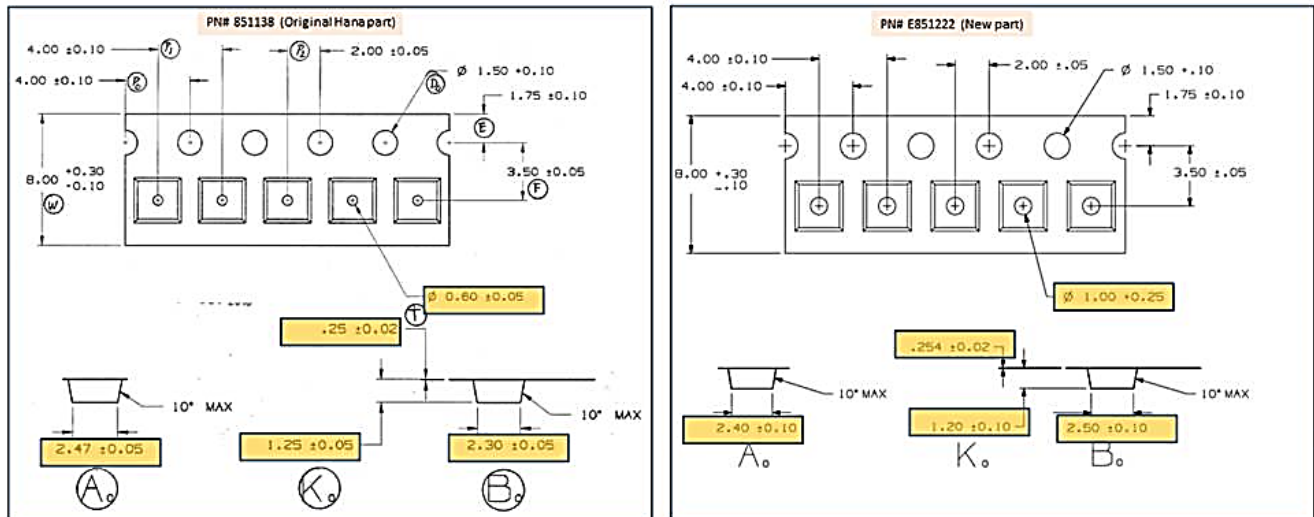
PCN Number:	20160726001	PCN Date:	07/27/2016
Title:	New Carrier Tape		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification
<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Packing/Shipping/Labeling
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Part number change
<input type="checkbox"/>		<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>		<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>		<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of a new carrier tape for the devices shown below. The material composition between the 2 carrier tapes is the same. A dimensional comparison summary is below:

Dimension	From (851138)	To (851222)
Ao	2.47 (+/- 0.05) mm	2.4 (+/- 0.1) mm
Bo	2.3 (+/- 0.05) mm	2.5 (+/- 0.1) mm
Ko	1.25 (+/- 0.05) mm	1.2 (+/- 0.1) mm
Thickness	0.25 (+/- 0.02) mm	0.254 (+/- 0.02) mm



Reason for Change:

Quality Improvement

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Not Applicable

Product Affected:			
1P1G125QDCKRG4Q1	SN74AHC1G86MDCKREP	SN74LVC1G97IDCKREP	TPS3803-01MDCKREP
CAHCT1G04QDCKRG4Q1	SN74AVC1T45DCKR	SN74LVC1T45MDCKREP	TPS3803-01QDCKREP
CAHCT1G125QDCKRG4Q	SN74AVCH1T45DCKR	SN74LVC2G04MDCKREP	TS5A9411DCKR
CLVC1G175MDCKREP	SN74LVC1G06MDCKREP	SN74LVC2G17MDCKREP	TS5A9411DCKT
SN74AHC1G02MDCKREP	SN74LVC1G11MDCKREP	SN74LVC2G34MDCKREP	

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com